

PRODUCT NUMBER
10076801-YXX-XXLF

PLATING

1= 0.76μm GOLD/GXT ON CONTACT
AREA, 2μm TIN MIN ON TAILS

4= 2.0 μ m TIN MIN FULL PLATED

5= 0.25μm GOLD/GXT ON CONTACT
AREA, 2μm TIN MIN ON TAILS

8= 0.38μm GOLD/GXT ON CONTACT
AREA, 2μm TIN MIN ON TAILS

1.27 μ m NICKEL MIN UNDERLAYER FOR ALL PLATING VERSIONS

LEAD FREE & RoHS COMPATIBLE

NOTE 7

- TOTAL NB OF POS
04 TO 72

PACKAGING NOTE 3.

PIN STYLE	POST	SOLDER
01	5.84	2.50
02	6.75	2.50
03	5.84	3.00
04	6.75	3.00
05	7.70	3.00
06	8.20	3.00
07	10.50	3.20
08	9.10	3.00
09	5.84	2.00

N x 2.54 MAX

NOTE 5

$$(N-1) \times 2.54$$

(7.6)

OPTIONAL PICK-UP CAP
(SEE NOTE 3)

2.54±0.08 TYP

NON-ACCUMULATIVE

2.54±0.08

1.05 MAX

FINISHED HOLE

RECOMMENDED HOLE PATTERN
1.6 mm THICK PCB DESIGN
RECOMMENDATION AS PER TA-897

NOTES:

1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
2. PIN MATERIAL : PHOSPHOR BRONZE
3. PACKAGING OPTIONS:
 - = POLY BAGS
 - A = TAPE & REEL WITH CAP, SEE TA840 FOR PRODUCT AVAILABILITY.
 - T = IN TUBE WITHOUT PICK-UP CAP
4. 9N MIN RETENTION IN EITHER DIRECTION
5. TO DETERMINE DIMENSIONS :
 - N = NUMBER OF POSITIONS PER ROW
 - EXAMPLE : 8 POS N x 2.54 = 20.32mm
6. UNDERPLATING : 1.27µm Ni MIN
7. ROHS COMPLIANT & COMPATIBLE PRODUCT SPECIFICATIONS
 - a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
 - b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 30 SECONDES IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
 - c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - d - LEGAL STATEMENT: SEE GS-47-0004

2.84 REF

2.54

0.62 SQUARE

POST ± 0.25

SOLDER ± 0.2

[illegible]